

## REMARKS

Upon entry of this Reply, new claims 93-99 will be present in this application. Claims 1-92 have been canceled. Reconsideration of the application is requested.

The rejection of claims based on U.S. Patent 6,372,114 to Ito, U.S. Patent 6,315,883 to Mayer et al., U.S. Patent 6,261,433 to Landau, or U.S. Patent 6,350,364 to Jang is moot as a result of the claim amendments appearing above. It is respectfully submitted that none of the four patents previously relied on discloses or suggests a planar conductive material structure usable as specified and including a substrate having a top portion that includes a surface portion and a cavity portion as recited, and a planar conductive layer formed within the cavity portion and on the surface portion such that a predetermined thickness range of the planar conductive layer over the surface portion is between one tenth and one half of the thickness of the planar conductive layer within the cavity portion as new claim 93 particularly defines. Similarly, none of the four patents previously relied on discloses or suggests a conductive bead structure usable in manufacturing an interconnect for an integrated circuit comprising a substrate having a top portion that includes a surface portion and a cavity portion, with a first cavity having a submicron width and a second cavity having a width larger than 10 microns, and conductive beads formed within each cavity such that each conductive bead protrudes above a level of the surface portion of the substrate and is confined within a respective cavity as new claim 97 particularly defines.

Each of newly added claims 93 and 97 is patentable for reasons discussed above. The remaining new claims appearing in this application are dependent claims and are patentable as well.

It is respectfully submitted that this application is now in condition for allowance. Should the Examiner have any questions after considering this Reply, the Examiner is invited to telephone the undersigned attorney.

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Respectfully submitted,

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